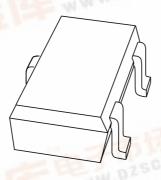
## DISCRETE SEMICONDUCTORS

# DATA SHEET



# BAP51-04W General purpose PIN diode

Preliminary specification







## General purpose PIN diode

## **BAP51-04W**

## **FEATURES**

- Two elements in series configuration in a small SMD plastic package
- Low diode capacitance
- Low diode forward resistance.

#### **APPLICATIONS**

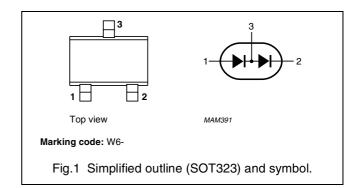
• General RF applications.

### **DESCRIPTION**

Two planar PIN diodes in series configuration in a SOT323 small SMD plastic package.

## **PINNING**

PIN	DESCRIPTION
1	anode
2	cathode
3	common connection



## **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode					
V <sub>R</sub>	continuous reverse voltage		_	50	V
I <sub>F</sub>	continuous forward current		_	50	mA
P <sub>tot</sub>	total power dissipation	T <sub>s</sub> = 90 °C	_	240	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-65	+150	°C

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## General purpose PIN diode

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## **ELECTRICAL CHARACTERISTICS**

 $T_i = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Per diode						
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 50 mA	_	0.95	1.1	٧
V <sub>R</sub>	reverse voltage	I <sub>R</sub> = 10 μA	50	_	_	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 50 V	_	_	100	nA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 0; f = 1 MHz	_	0.4	_	pF
		V <sub>R</sub> = 1 V; f = 1 MHz	_	0.3	0.55	pF
		V <sub>R</sub> = 5 V; f = 1 MHz	_	0.2	0.35	pF
r <sub>D</sub>	diode forward resistance	I <sub>F</sub> = 0.5 mA; f = 100 MHz; note 1	_	5.5	9	Ω
		I <sub>F</sub> = 1 mA; f = 100 MHz; note 1	_	3.6	6.5	Ω
		I <sub>F</sub> = 10 mA; f = 100 MHz; note 1	_	1.5	2.5	Ω
τ <sub>L</sub>	charge carrier life time	when switched from $I_F$ = 10 mA to $I_R$ = 6 mA; $R_L$ = 100 $\Omega$ ; measured at $I_R$ = 3 mA	-	550	_	ns
L <sub>S</sub>	series inductance	I <sub>F</sub> = 10 mA; f = 100 MHz	_	1.6	_	nH

### Note

1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	250	K/W

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## General purpose PIN diode

## **BAP51-04W**

## **GRAPHICAL DATA**

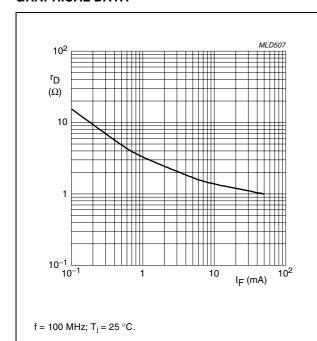


Fig.2 Forward resistance as a function of forward current; typical values.

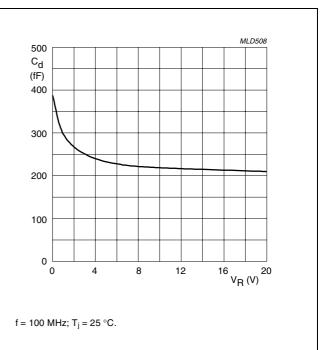
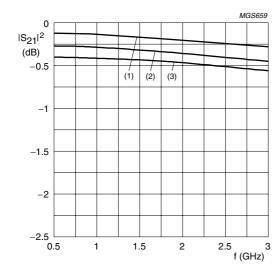


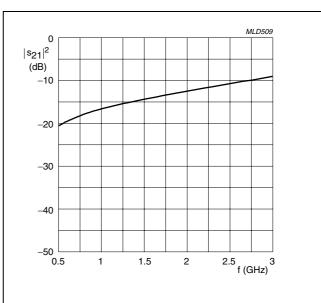
Fig.3 Diode capacitance as a function of reverse voltage; typical values.



- (1)  $I_F = 10 \text{ mA}.$
- (2)  $I_F = 1 \text{ mA}$
- (3)  $I_F = 0.5 \text{ mA}$

Diode inserted in series with a 50  $\,\Omega$  stripline circuit and biased via the analyzer Tee network. T  $_{amb}$  = 25  $^{\circ}C$  .

Fig.4 Insertion loss  $(|s_{21}|^2)$  of the diode as a function of frequency; typical values.



Diode zero biased and inserted in series with a 50  $\Omega$  stripline circuit.  $T_{amb}$  = 25  $^{\circ}C.$ 

Fig.5 Isolation ( $|s_{21}|^2$ ) of the diode as a function of frequency; typical values.

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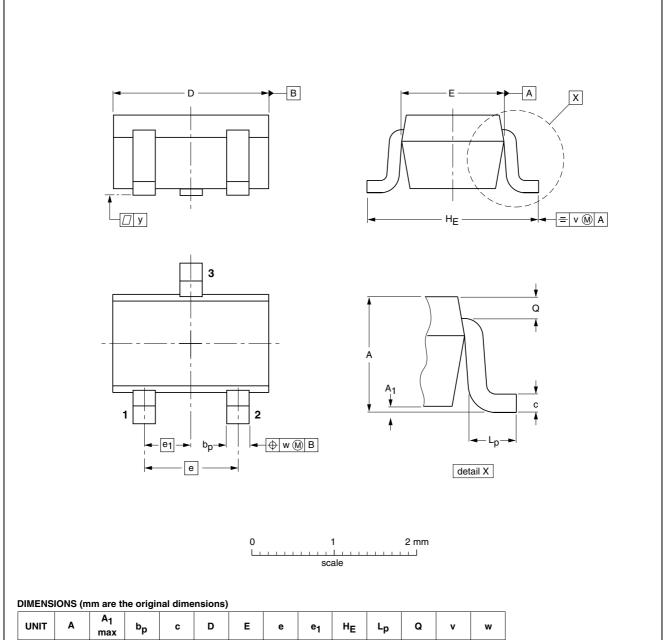
## General purpose PIN diode

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## **PACKAGE OUTLINE**

## Plastic surface mounted package; 3 leads

**SOT323** 



UNIT	A	A <sub>1</sub> max	bp	С	D	E	е	e <sub>1</sub>	HE	Lp	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE		REFER	EUROPEAN ISSUE DATE				
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT323			SC-70			97-02-28	

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## General purpose PIN diode

**BAP51-04W** 

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DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

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Limiting values definition—Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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